

an electrically conductive joint arranged between the electric element and the electrically conductive layer to connect electrically the electric element and the electrically conductive layer to each other;

a molding resin covering at least partially the electric element and the electrically conductive joint; and

an electrically insulating layer contacting at least partially the electrically conductive layer;

wherein the electrically conductive layer includes a first layer of Nickel-base metal, and a second layer of Copper-base metal extends at least partially between the first layer and the electric element, and

the electrically insulating layer is juxtaposed with a part of the second layer in a direction perpendicular to a thickness direction of the electrically conductive layer so that surfaces of the electrically insulating layer and the part of the second layer both prevented from facing to the electric element extend along a common flat face.

5. (Amended) The semiconductor module according to claim 4, wherein the first layer extends on the surface of the electrically insulating layer along the common flat face.

6. (Amended) A semiconductor module comprising:

at least one electric element including a semiconductor chip;

an electrically conductive layer connected electrically to the electric element;

an electrically conductive joint arranged between the electric element and the electrically conductive layer to connect electrically the electric element and the electrically conductive layer to each other;

a molding resin covering at least partially the electric element and the electrically conductive joint; and

an electrically insulating layer contacting at least partially the electrically conductive layer;

wherein the electrically conductive layer includes a first layer of Nickel-base metal, and a second layer of Copper-base metal extends at least partially between the first layer and the electric element, and

a surface of the first layer prevented from facing to the electric element extends between the electric element and a surface of the electrically insulating layer prevented from facing to the electric element, in a thickness direction of the electrically conductive layer.

8. (Amended) A semiconductor module comprising:

at least one electric element including a semiconductor chip;

an electrically conductive layer connected electrically to the electric element;

an electrically conductive joint arranged between the electric element and the electrically conductive layer to connect electrically the electric element and the electrically conductive layer to each other;

a molding resin covering at least partially the electric element and the electrically conductive joint;

an electrically insulating layer contacting at least partially the electrically conductive layer; and

a film of Nickel-base metal extending on a surface of the electrically insulating layer prevented from facing to the electric element.

9. (Amended) A semiconductor module comprising:

at least one electric element including a semiconductor chip;

an electrically conductive layer connected electrically to the electric element;

an electrically conductive joint arranged between the electric element and the electrically conductive layer to connect electrically the electric element and the electrically conductive layer to each other;

a molding resin covering at least partially the electric element and the electrically conductive joint;

an electrically insulating layer contacting at least partially the electrically conductive layer; and

a metallic film extending on a surface of the electrically insulating layer prevented from facing to the electric element, wherein the metallic film is electrically connected to the electrically conductive layer.

10. (Amended) A semiconductor module comprising:

at least one electric element including a semiconductor chip;

an electrically conductive layer connected electrically to the electric element;

an electrically conductive joint arranged between the electric element and the electrically conductive layer to connect electrically the electric element and the electrically conductive layer to each other;

a molding resin covering at least partially the electric element and the electrically conductive joint;

an electrically insulating layer contacting at least partially the electrically conductive layer; and

a metallic film extending on a surface of the electrically insulating layer prevented from facing to the electric element, wherein the metallic film is magnetically permeable.

Please add the following claim:

22. (New) The semiconductor module according to claim 4, wherein a boundary between the part of the second layer of said Copper-base metal and the first layer of said Nickel-base metal extends along the common flat face.